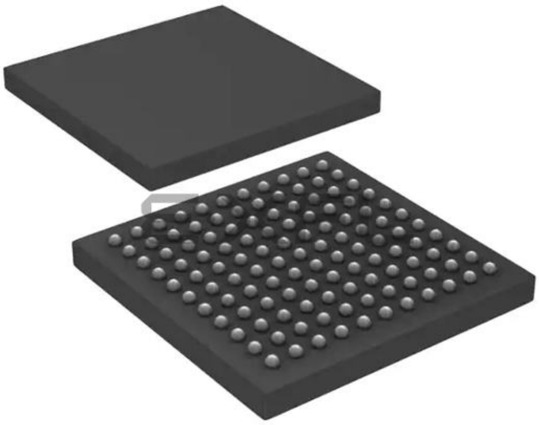

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	Ethernet, I²C, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	83
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	121-TFBGA
Supplier Device Package	121-TFBGA (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx675f512lt-80i-bg

2.5 ICSP Pins

The PGECx and PGEDx pins are used for In-Circuit Serial Programming™ (ICSP™) and debugging. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® ICD 3 or MPLAB® REAL ICE™.

For more information on ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

- *"Using MPLAB® ICD 3"* (poster) (DS50001765)
- *"MPLAB® ICD 3 Design Advisory"* (DS50001764)
- *"MPLAB® REAL ICE™ In-Circuit Emulator User's Guide" (*DS50001616)
- *"Using MPLAB® REAL ICE™ Emulator"* (poster) (DS50001749)

2.6 JTAG

The TMS, TDO, TDI and TCK pins are used for testing and debugging according to the Joint Test Action Group (JTAG) standard. It is recommended to keep the trace length between the JTAG connector and the JTAG pins on the device as short as possible. If the JTAG connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the TMS, TDO, TDI and TCK pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input low (V_{IL}) requirements.

2.7 Trace

The trace pins can be connected to a hardware-trace-enabled programmer to provide a compress real time instruction trace. When used for trace the TRD3, TRD2, TRD1, TRD0 and TRCLK pins should be dedicated for this use. The trace hardware requires a 22Ω series resistor between the trace pins and the trace connector.

2.8 External Oscillator Pins

Many MCUs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator. Refer to **Section 8.0 "Oscillator Configuration"** for details.

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is illustrated in Figure 2-3.

FIGURE 2-3: SUGGESTED OSCILLATOR CIRCUIT PLACEMENT

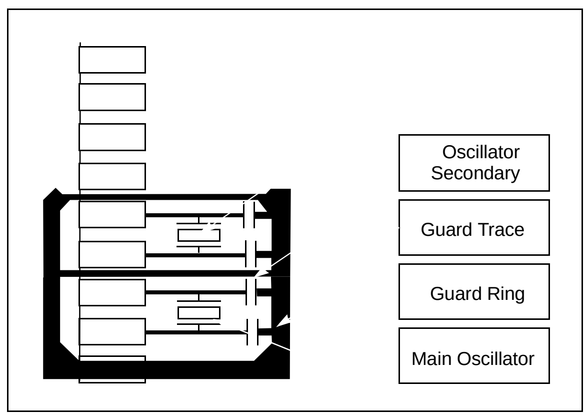


TABLE 4-1: SFR MEMORY MAP

Peripheral	Virtual Address	
	Base	Offset Start
Watchdog Timer	0xBF80	0x0000
RTCC		0x0200
Timer1-Timer5		0x0600
Input Capture 1-5		0x2000
Output Compare 1-5		0x3000
I2C1-I2C5		0x5000
SPI1-SPI4		0x5800
UART1-UART6		0x6000
PMP		0x7000
ADC		0x9000
CVREF		0x9800
Comparator		0xA000
Oscillator		0xF000
Device and Revision ID		0xF200
Flash Controller		0xF400
Reset		0xF600
Interrupts	0xBF88	0x1000
Bus Matrix		0x2000
DMA		0x3000
Prefetch		0x4000
USB		0x5040
PORTA-PORTG		0x6000
Ethernet		0x9000
Configuration	0xBFC0	0x2FF0

TABLE 7-1: INTERRUPT IRQ, VECTOR AND BIT LOCATION (CONTINUED)

Interrupt Source[(1)]	IRQ Number	Vector Number	Interrupt Bit Location			
			Flag	Enable	Priority	Sub-Priority
IC3E – Input Capture 3 Error	63	13	IFS1<31>	IEC1<31>	IPC3<12:10>	IPC3<9:8>
IC4E – Input Capture 4 Error	64	17	IFS2<0>	IEC2<0>	IPC4<12:10>	IPC4<9:8>
IC5E – Input Capture 5 Error	65	21	IFS2<1>	IEC2<1>	IPC5<12:10>	IPC5<9:8>
PMPE – Parallel Master Port Error	66	28	IFS2<2>	IEC2<2>	IPC7<4:2>	IPC7<1:0>
U4E – UART4 Error	67	49	IFS2<3>	IEC2<3>	IPC12<12:10>	IPC12<9:8>
U4RX – UART4 Receiver	68	49	IFS2<4>	IEC2<4>	IPC12<12:10>	IPC12<9:8>
U4TX – UART4 Transmitter	69	49	IFS2<5>	IEC2<5>	IPC12<12:10>	IPC12<9:8>
U6E – UART6 Error	70	50	IFS2<6>	IEC2<6>	IPC12<20:18>	IPC12<17:16>
U6RX – UART6 Receiver	71	50	IFS2<7>	IEC2<7>	IPC12<20:18>	IPC12<17:16>
U6TX – UART6 Transmitter	72	50	IFS2<8>	IEC2<8>	IPC12<20:18>	IPC12<17:16>
U5E – UART5 Error	73	51	IFS2<9>	IEC2<9>	IPC12<28:26>	IPC12<25:24>
U5RX – UART5 Receiver	74	51	IFS2<10>	IEC2<10>	IPC12<28:26>	IPC12<25:24>
U5TX – UART5 Transmitter	75	51	IFS2<11>	IEC2<11>	IPC12<28:26>	IPC12<25:24>
(Reserved)	—	—	—	—	—	—
Lowest Natural Order Priority						

Note 1: Not all interrupt sources are available on all devices. See **TABLE 1: "PIC32MX5XX USB and CAN Features"**, **TABLE 2: "PIC32MX6XX USB and Ethernet Features"** and **TABLE 3: "PIC32MX7XX USB, Ethernet, and CAN Features"** for the list of available peripherals.

TABLE 7-7: INTERRUPT REGISTER MAP FOR PIC32MX764F128L, PIC32MX775F256L, PIC32MX775F512L AND PIC32MX795F512L DEVICES

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
1000	INTCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SS0	0000
		15:0	—	—	—	MVEC	—	TPC<2:0>			—	—	—	INT4EP	INT3EP	INT2EP	INT1EP	INT0EP	0000
1010	INTSTAT(3)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	SRIPL<2:0>			—	—	VEC<5:0>						0000
1020	IPTMR	31:16	IPTMR<31:0>																0000
		15:0																	0000
1030	IFS0	31:16	I2C1MIF	I2C1SIF	I2C1BIF	U1TXIF SPI3TXIF I2C3MIF	U1RXIF SPI3RXIF I2C3SIF	U1EIF SPI3EIF I2C3BIF	SPI1TXIF	SPI1RXIF	SPI1EIF	OC5IF	IC5IF	T5IF	INT4IF	OC4IF	IC4IF	T4IF	0000
		15:0	INT3IF	OC3IF	IC3IF	T3IF	INT2IF	OC2IF	IC2IF	T2IF	INT1IF	OC1IF	IC1IF	T1IF	INT0IF	CS1IF	CS0IF	CTIF	0000
1040	IFS1	31:16	IC3EIF	IC2EIF	IC1EIF	ETHIF	CAN2IF(2)	CAN1IF	USBIF	FCEIF	DMA7IF(2)	DMA6IF(2)	DMA5IF(2)	DMA4IF(2)	DMA3IF	DMA2IF	DMA1IF	DMA0IF	0000
		15:0	RTCCIF	FSCMIF	I2C2MIF	I2C2SIF	I2C2BIF	U2TXIF SPI4TXIF I2C5MIF	U2RXIF SPI4RXIF I2C5SIF	U2EIF SPI4EIF I2C5BIF	U3TXIF SPI2TXIF I2C4MIF	U3RXIF SPI2RXIF I2C4SIF	U3EIF SPI2EIF I2C4BIF	CMP2IF	CMP1IF	PMPIF	AD1IF	CNIF	0000
1050	IFS2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	U5TXIF	U5RXIF	U5EIF	U6TXIF	U6RXIF	U6EIF	U4TXIF	U4RXIF	U4EIF	PMPEIF	IC5EIF	IC4EIF	0000
1060	IEC0	31:16	I2C1MIE	I2C1SIE	I2C1BIE	U1TXIE SPI3TXIE I2C3MIE	U1RXIE SPI3RXIE I2C3SIE	U1EIE SPI3EIE I2C3BIE	SPI1TXIE	SPI1RXIE	SPI1EIE	OC5IE	IC5IE	T5IE	INT4IE	OC4IE	IC4IE	T4IE	0000
		15:0	INT3IE	OC3IE	IC3IE	T3IE	INT2IE	OC2IE	IC2IE	T2IE	INT1IE	OC1IE	IC1IE	T1IE	INT0IE	CS1IE	CS0IE	CTIE	0000
1070	IEC1	31:16	IC3EIE	IC2EIE	IC1EIE	ETHIE	CAN2IE(2)	CAN1IE	USBIE	FCEIE	DMA7IE(2)	DMA6IE(2)	DMA5IE(2)	DMA4IE(2)	DMA3IE	DMA2IE	DMA1IE	DMA0IE	0000
		15:0	RTCCIE	FSCMIE	I2C2MIE	I2C2SIE	I2C2BIE	U2TXIE SPI4TXIE I2C5MIE	U2RXIE SPI4RXIE I2C5SIE	U2EIE SPI4EIE I2C5BIE	U3TXIE SPI2TXIE I2C4MIE	U3RXIE SPI2RXIE I2C4SIE	U3EIE SPI2EIE I2C4BIE	CMP2IE	CMP1IE	PMPIE	AD1IE	CNIE	0000
1080	IEC2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	U5TXIE	U5RXIE	U5EIE	U6TXIE	U6RXIE	U6EIE	U4TXIE	U4RXIE	U4EIE	PMPEIE	IC5EIE	IC4EIE	0000
1090	IPC0	31:16	—	—	—	INT0IP<2:0>			INT0IS<1:0>		—	—	—	CS1IP<2:0>			CS1IS<1:0>		0000
		15:0	—	—	—	CS0IP<2:0>			CS0IS<1:0>		—	—	—	CTIP<2:0>			CTIS<1:0>		0000
10A0	IPC1	31:16	—	—	—	INT1IP<2:0>			INT1IS<1:0>		—	—	—	OC1IP<2:0>			OC1IS<1:0>		0000
		15:0	—	—	—	IC1IP<2:0>			IC1IS<1:0>		—	—	—	T1IP<2:0>			T1IS<1:0>		0000
10B0	IPC2	31:16	—	—	—	INT2IP<2:0>			INT2IS<1:0>		—	—	—	OC2IP<2:0>			OC2IS<1:0>		0000
		15:0	—	—	—	IC2IP<2:0>			IC2IS<1:0>		—	—	—	T2IP<2:0>			T2IS<1:0>		0000
10C0	IPC3	31:16	—	—	—	INT3IP<2:0>			INT3IS<1:0>		—	—	—	OC3IP<2:0>			OC3IS<1:0>		0000
		15:0	—	—	—	IC3IP<2:0>			IC3IS<1:0>		—	—	—	T3IP<2:0>			T3IS<1:0>		0000

Legend: x = unknown value on Reset; — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

Note 1: Except where noted, all registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

2: This bit is unimplemented on PIC32MX764F128L device.

3: This register does not have associated CLR, SET, and INV registers.

REGISTER 8-1: OSCCON: OSCILLATOR CONTROL REGISTER (CONTINUED)

bit 18-16 **PLLMULT<2:0>:** Phase-Locked Loop (PLL) Multiplier bits

111 = Clock is multiplied by 24
110 = Clock is multiplied by 21
101 = Clock is multiplied by 20
100 = Clock is multiplied by 19
011 = Clock is multiplied by 18
010 = Clock is multiplied by 17
001 = Clock is multiplied by 16
000 = Clock is multiplied by 15

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **COSC<2:0>:** Current Oscillator Selection bits

111 = Internal Fast RC (FRC) Oscillator divided by OSCCON<FRCDIV> bits
110 = Internal Fast RC (FRC) Oscillator divided by 16
101 = Internal Low-Power RC (LPRC) Oscillator
100 = Secondary Oscillator (SOSC)
011 = Primary Oscillator (POSC) with PLL module (XTPLL, HSPLL or ECPLL)
010 = Primary Oscillator (POSC) (XT, HS or EC)
001 = Internal Fast RC Oscillator with PLL module via Postscaler (FRCPLL)
000 = Internal Fast RC (FRC) Oscillator

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **NOSC<2:0>:** New Oscillator Selection bits

111 = Internal Fast RC Oscillator (FRC) divided by OSCCON<FRCDIV> bits
110 = Internal Fast RC Oscillator (FRC) divided by 16
101 = Internal Low-Power RC (LPRC) Oscillator
100 = Secondary Oscillator (SOSC)
011 = Primary Oscillator with PLL module (XTPLL, HSPLL or ECPLL)
010 = Primary Oscillator (XT, HS or EC)
001 = Internal Fast Internal RC Oscillator with PLL module via Postscaler (FRCPLL)
000 = Internal Fast Internal RC Oscillator (FRC)

On Reset, these bits are set to the value of the FNOSC Configuration bits (DEVCFG1<2:0>).

bit 7 **CLKLOCK:** Clock Selection Lock Enable bit

If clock switching and monitoring is disabled (FCKSM<1:0> = 1x):
1 = Clock and PLL selections are locked
0 = Clock and PLL selections are not locked and may be modified

If clock switching and monitoring is enabled (FCKSM<1:0> = 0x):
Clock and PLL selections are never locked and may be modified.

bit 6 **ULOCK:** USB PLL Lock Status bit

1 = Indicates that the USB PLL module is in lock or USB PLL module start-up timer is satisfied
0 = Indicates that the USB PLL module is out of lock or USB PLL module start-up timer is in progress or USB PLL is disabled

bit 5 **SLOCK:** PLL Lock Status bit

1 = PLL module is in lock or PLL module start-up timer is satisfied
0 = PLL module is out of lock, PLL start-up timer is running or PLL is disabled

bit 4 **SLPEN:** Sleep Mode Enable bit

1 = Device will enter Sleep mode when a WAIT instruction is executed
0 = Device will enter Idle mode when a WAIT instruction is executed

bit 3 **CF:** Clock Fail Detect bit

1 = FSCM has detected a clock failure
0 = No clock failure has been detected

Note:	Writes to this register require an unlock sequence. Refer to **Section 6. "Oscillator"** (DS60001112) in the *"PIC32 Family Reference Manual"* for details.

REGISTER 9-8: CHEW3: CACHE WORD 3

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	CHEW3<31:24>							
23:16	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	CHEW3<23:16>							
15:8	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	CHEW3<15:8>							
7:0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	CHEW3<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-0 **CHEW3<31:0>:** Word 3 of the cache line selected by CHEIDX<3:0> bits (CHEACC<3:0>)
Readable only if the device is not code-protected.

Note: This register is a window into the cache data array and is only readable if the device is not code-protected.

REGISTER 9-9: CHELRU: CACHE LRU REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	R-0
	—	—	—	—	—	—	—	CHELRU<24>
23:16	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	CHELRU<23:16>							
15:8	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	CHELRU<15:8>							
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	CHELRU<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-25 **Unimplemented:** Write ‘0’; ignore read

bit 24-0 **CHELRU<24:0>:** Cache Least Recently Used State Encoding bits
Indicates the pseudo-LRU state of the cache.

REGISTER 14-1: TXCON: TYPE B TIMER CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
	ON(1,3)	—	SIDL(4)	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	U-0
	TGATE(3)	TCKPS<2:0>(3)			T32(2)	—	TCS(3)	—

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as ‘0’

bit 15 **ON:** Timer On bit(1,3)
1 = Module is enabled
0 = Module is disabled

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **SIDL:** Stop in Idle Mode bit(4)
1 = Discontinue operation when device enters Idle mode
0 = Continue operation when device is in Idle mode

bit 12-8 **Unimplemented:** Read as ‘0’

bit 7 **TGATE:** Timer Gated Time Accumulation Enable bit(3)
When TCS = 1:
This bit is ignored and is read as ‘0’.
When TCS = 0:
1 = Gated time accumulation is enabled
0 = Gated time accumulation is disabled

bit 6-4 **TCKPS<2:0>:** Timer Input Clock Prescale Select bits(3)
111 = 1:256 prescale value
110 = 1:64 prescale value
101 = 1:32 prescale value
100 = 1:16 prescale value
011 = 1:8 prescale value
010 = 1:4 prescale value
001 = 1:2 prescale value
000 = 1:1 prescale value

Note 1: When using the 1:1 PBCLK divisor, the user’s software should not read/write the peripheral SFRs in the SYSCLK cycle immediately following the instruction that clears the module’s ON bit.
2: This bit is only available on even numbered timers (Timer2 and Timer4).
3: While operating in 32-bit mode, this bit has no effect for odd numbered timers (Timer1, Timer3, and Timer5). All timer functions are set through the even numbered timers.
4: While operating in 32-bit mode, this bit must be cleared on odd numbered timers to enable the 32-bit timer in Idle mode.

18.0 SERIAL PERIPHERAL INTERFACE (SPI)

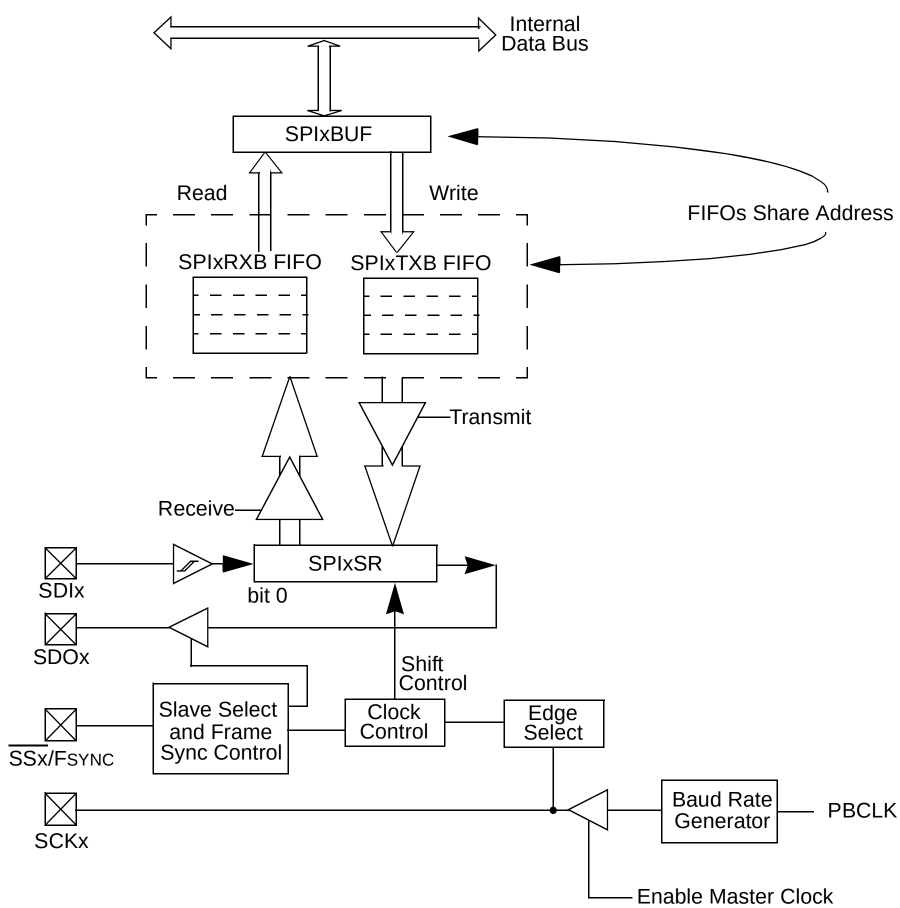
Note:	This data sheet summarizes the features of the PIC32MX5XX/6XX/7XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 23. "Serial Peripheral Interface (SPI)"** (DS60001106) in the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

The SPI module is a synchronous serial interface that is useful for communicating with external peripherals and other microcontroller devices. These peripheral devices may be Serial EEPROMs, Shift registers, display drivers, Analog-to-Digital Converters, etc. The PIC32 SPI module is compatible with Motorola® SPI and SIOP interfaces.

The following are some of the key features of the SPI module:

- Master mode and Slave mode support
- Four different clock formats
- Enhanced Framed SPI protocol support
- User-configurable 8-bit, 16-bit and 32-bit data width
- Separate SPI FIFO buffers for receive and transmit
  - FIFO buffers act as 4/8/16-level deep FIFOs based on 32/16/8-bit data width
- Programmable interrupt event on every 8-bit, 16-bit and 32-bit data transfer
- Operation during Sleep and Idle modes
- Fast bit manipulation using CLR, SET and INV registers

FIGURE 18-1: SPI MODULE BLOCK DIAGRAM



Note: Access SPIxTXB and SPIxRXB FIFOs via SPIxBUF register.

REGISTER 25-19: ETHMCOLFRM: ETHERNET CONTROLLER MULTIPLE COLLISION FRAMES STATISTICS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	MCOLFRMCNT<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	MCOLFRMCNT<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as ‘0’

bit 15-0 **MCOLFRMCNT<15:0>:** Multiple Collision Frame Count bits

Increment count for frames that were successfully transmitted after there was more than one collision.

Note 1: This register is only used for TX operations.

2: This register is automatically cleared by hardware after a read operation, unless the byte enables for bytes 0/1 are ‘0’.

3: It is recommended to use the SET, CLR, or INV registers to set or clear any bit in this register. Setting or clearing any bits in this register should only be done for debug/test purposes.

REGISTER 25-20: ETHFRMRXOK: ETHERNET CONTROLLER FRAMES RECEIVED OK STATISTICS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	FRMRXOKCNT<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	FRMRXOKCNT<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-0 **FRMRXOKCNT<15:0>:** Frames Received OK Count bits

Increment count for frames received successfully by the RX Filter. This count will not be incremented if there is a Frame Check Sequence (FCS) or Alignment error.

Note 1: This register is only used for RX operations.

2: This register is automatically cleared by hardware after a read operation, unless the byte enables for bytes 0/1 are '0'.

3: It is recommended to use the SET, CLR, or INV registers to set or clear any bit in this register. Setting or clearing any bits in this register should only be done for debug/test purposes.

REGISTER 25-25: EMAC1IPGT: ETHERNET CONTROLLER MAC BACK-TO-BACK INTERPACKET GAP REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	R/W-0	R/W-0	R/W-1	R/W-0	R/W-0	R/W-1	R/W-0
	—	B2BIPKTGP<6:0>						

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-7 **Unimplemented:** Read as ‘0’

bit 6-0 **B2BIPKTGP<6:0>:** Back-to-Back Interpacket Gap bits

This is a programmable field representing the nibble time offset of the minimum possible period between the end of any transmitted packet, to the beginning of the next. In Full-Duplex mode, the register value should be the desired period in nibble times minus 3. In Half-Duplex mode, the register value should be the desired period in nibble times minus 6. In Full-Duplex the recommended setting is 0x15 (21d), which represents the minimum IPG of 0.96 µs (in 100 Mbps) or 9.6 µs (in 10 Mbps). In Half-Duplex mode, the recommended setting is 0x12 (18d), which also represents the minimum IPG of 0.96 µs (in 100 Mbps) or 9.6 µs (in 10 Mbps).

Note:	Both 16-bit and 32-bit accesses are allowed to these registers (including the SET, CLR and INV registers). 8-bit accesses are not allowed and are ignored by the hardware.

REGISTER 29-3: DEVCFG2: DEVICE CONFIGURATION WORD 2 (CONTINUED)

bit 2-0	**FPLLIDIV<2:0>:** PLL Input Divider bits `111` = 12x divider `110` = 10x divider `101` = 6x divider `100` = 5x divider `011` = 4x divider `010` = 3x divider `001` = 2x divider `000` = 1x divider

REGISTER 29-4: DEVCFG3: DEVICE CONFIGURATION WORD 3

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/P	R/P	r-1	r-1	r-1	R/P	R/P	R/P
	FVBUSONIO	FUSBIDIO	—	—	—	FCANIO(1)	FETHIO(2)	FMIIEN(2)
23:16	r-1	r-1	r-1	r-1	r-1	R/P	R/P	R/P
	—	—	—	—	—	FSRSSEL<2:0>		
15:8	R/P	R/P	R/P	R/P	R/P	R/P	R/P	R/P
	USERID<15:8>							
7:0	R/P	R/P	R/P	R/P	R/P	R/P	R/P	R/P
	USERID<7:0>							

Legend:	r = Reserved bit	P = Programmable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31 **FVBUSONIO:** USB VBUSON Selection bit
1 = VBUSON pin is controlled by the USB module
0 = VBUSON pin is controlled by the port function

bit 30 **FUSBIDIO:** USB USBID Selection bit
1 = USBID pin is controlled by the USB module
0 = USBID pin is controlled by the port function

bit 29-27 **Reserved:** Write ‘1’

bit 26 **FCANIO:** CAN I/O Pin Selection bit(1)
1 = Default CAN I/O Pins
0 = Alternate CAN I/O Pins

bit 25 **FETHIO:** Ethernet I/O Pin Selection bit(2)
1 = Default Ethernet I/O Pins
0 = Alternate Ethernet I/O Pins

bit 24 **FMIIEN:** Ethernet MII Enable bit(2)
1 = MII is enabled
0 = RMII is enabled

bit 23-19 **Reserved:** Write ‘1’

bit 18-16 **FSRSSEL<2:0>:** SRS Select bits
111 = Assign Interrupt Priority 7 to a shadow register set
110 = Assign Interrupt Priority 6 to a shadow register set
•
•
•
001 = Assign Interrupt Priority 1 to a shadow register set
000 = All interrupt priorities are assigned to a shadow register set

bit 15-0 **USERID<15:0>:** User ID bits
This is a 16-bit value that is user-defined and is readable via ICSP™ and JTAG.

Note 1: This bit is Reserved and reads ‘1’ on PIC32MX664/675/695 devices.
2: This bit is Reserved and reads ‘1’ on PIC32MX534/564/575 devices.

29.2 On-Chip Voltage Regulator

All PIC32MX5XX/6XX/7XX devices' core and digital logic are designed to operate at a nominal 1.8V. To simplify system designs, most devices in the PIC32MX-5XX/6XX/7XX family incorporate an on-chip regulator providing the required core logic voltage from VDD.

A low-ESR capacitor (such as tantalum) must be connected to the VCAP pin (see Figure 29-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in **Section 32.1 "DC Characteristics"**.

Note:	It is important that the low-ESR capacitor is placed as close as possible to the VCAP pin.

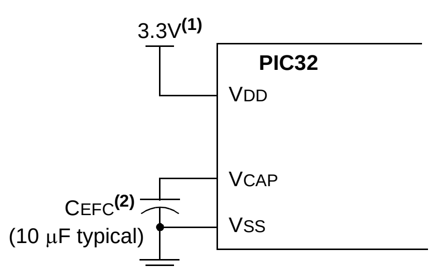
29.2.1 ON-CHIP REGULATOR AND POR

It takes a fixed delay for the on-chip regulator to generate an output. During this time, designated as TPU, code execution is disabled. TPU is applied every time the device resumes operation after any power-down, including Sleep mode.

29.2.2 ON-CHIP REGULATOR AND BOR

PIC32MX5XX/6XX/7XX devices also have a simple brown-out capability. If the voltage supplied to the regulator is inadequate to maintain a regulated level, the regulator Reset circuitry will generate a Brown-out Reset (BOR). This event is captured by the BOR flag bit (RCON<1>). The brown-out voltage levels are specified in **Section 32.1 "DC Characteristics"**.

FIGURE 29-1: CONNECTIONS FOR THE ON-CHIP REGULATOR



Note 1: These are typical operating voltages. Refer to **Section 32.1 "DC Characteristics"** for the full operating ranges of VDD.

2: It is important that the low-ESR capacitor is placed as close as possible to the VCAP pin.

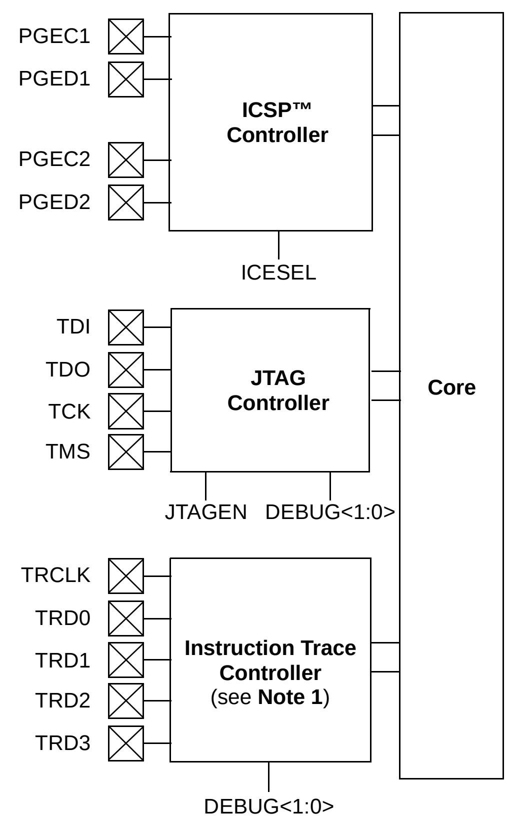
29.3 Programming and Diagnostics

PIC32MX5XX/6XX/7XX devices provide a complete range of programming and diagnostic features that can increase the flexibility of any application using them. These features allow system designers to include:

- Simplified field programmability using two-wire In-Circuit Serial Programming™ (ICSP™) interfaces
- Debugging using ICSP
- Programming and debugging capabilities using the EJTAG extension of JTAG
- JTAG boundary scan testing for device and board diagnostics

PIC32 devices incorporate two programming and diagnostic modules, and a trace controller, that provide a range of functions to the application developer.

FIGURE 29-2: PROGRAMMING, DEBUGGING, AND TRACE PORTS BLOCK DIAGRAM



Note 1: Trace is not available on 64-pin devices.

TABLE 32-8: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
	VIL	**Input Low Voltage**					
DI10		I/O Pins:					
		with TTL Buffer	VSS	—	0.15 VDD	V	
		with Schmitt Trigger Buffer	VSS	—	0.2 VDD	V	
DI15		$\overline{\text{MCLR}}$(2)	VSS	—	0.2 VDD	V	
DI16		OSC1 (XT mode)	VSS	—	0.2 VDD	V	**(Note 4)**
DI17		OSC1 (HS mode)	VSS	—	0.2 VDD	V	**(Note 4)**
DI18		SDAx, SCLx	VSS	—	0.3 VDD	V	SMBus disabled **(Note 4)**
DI19		SDAx, SCLx	VSS	—	0.8	V	SMBus enabled **(Note 4)**
	VIH	**Input High Voltage**					
DI20		I/O Pins not 5V-tolerant(5)	0.65 VDD	—	VDD	V	**(Note 4,6)**
		I/O Pins 5V-tolerant with PMP(5)	0.25 VDD + 0.8V	—	5.5	V	**(Note 4,6)**
		I/O Pins 5V-tolerant(5)	0.65 VDD	—	5.5	V	
DI28		SDAx, SCLx	0.65 VDD	—	5.5	V	SMBus disabled **(Note 4,6)**
DI29		SDAx, SCLx	2.1	—	5.5	V	SMBus enabled, 2.3V ≤ VPIN ≤ 5.5 **(Note 4,6)**
DI30	ICNPU	**Change Notification Pull-up Current**	—	—	-50	µA	VDD = 3.3V, VPIN = VSS **(Note 3,6)**
DI31	ICNPD	**Change Notification Pull-down Current(4)**	—	50	—	µA	VDD = 3.3V, VPIN = VDD

Note 1: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: This parameter is characterized, but not tested in manufacturing.

5: See the **“Device Pin Tables”** section for the 5V-tolerant pins.

6: The VIH specification is only in relation to externally applied inputs and not with respect to the user-selectable pull-ups. Externally applied high impedance or open drain input signals utilizing the PIC32 internal pull-ups are guaranteed to be recognized as a logic “high” internally to the PIC32 device, provided that the external load does not exceed the maximum value of ICNPU.

7: VIL source < (VSS - 0.3). Characterized but not tested.

8: VIH source > (VDD + 0.3) for non-5V tolerant pins only.

9: Digital 5V tolerant pins do not have an internal high side diode to VDD, and therefore, cannot tolerate any “positive” input injection current.

10: Injection currents > | 0 | can affect the ADC results by approximately 4 to 6 counts (i.e., VIH Source > (VDD + 0.3) or VIL source < (VSS - 0.3)).

11: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the “absolute instantaneous” sum of the input injection currents from all pins do not exceed the specified limit. If **Note 7**, IICL = (((Vss - 0.3) - VIL source) / Rs). If **Note 8**, IICH = ((IICH source - (VDD + 0.3)) / RS). RS = Resistance between input source voltage and device pin. If (VSS - 0.3) ≤ VSOURCE ≤ (VDD + 0.3), injection current = 0.

TABLE 32-13: COMPARATOR SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions (see Note 3): 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Comments**
D300	V_{IOFF}	Input Offset Voltage	—	±7.5	±25	mV	$AV_{DD} = V_{DD}$, $AV_{SS} = V_{SS}$
D301	V_{ICM}	Input Common Mode Voltage	0	—	V_{DD}	V	$AV_{DD} = V_{DD}$, $AV_{SS} = V_{SS}$ **(Note 2)**
D302	CMRR	Common Mode Rejection Ratio	55	—	—	dB	Max $V_{ICM} = (V_{DD} - 1)$V **(Note 2)**
D303	T_{RESP}	Response Time	—	150	400	ns	$AV_{DD} = V_{DD}$, $AV_{SS} = V_{SS}$ **(Notes 1, 2)**
D304	$ON2_{OV}$	Comparator Enabled to Output Valid	—	—	10	µs	Comparator module is configured before setting the comparator ON bit **(Note 2)**
D305	IV_{REF}	Internal Voltage Reference	0.57	0.6	0.63	V	For devices without BGSEL<1:0>
			1.14	1.2	1.26	V	BGSEL<1:0> = `00`
			0.57	0.6	0.63	V	BGSEL<1:0> = `01`

Note 1: Response time measured with one comparator input at $(V_{DD} – 1.5)/2$, while the other input transitions from V_{SS} to V_{DD}.

2: These parameters are characterized but not tested.

3: The Comparator module is functional at $V_{BORMIN} < V_{DD} < V_{DDMIN}$, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

FIGURE 32-12: SPIx MODULE SLAVE MODE (CKE = 0) TIMING CHARACTERISTICS

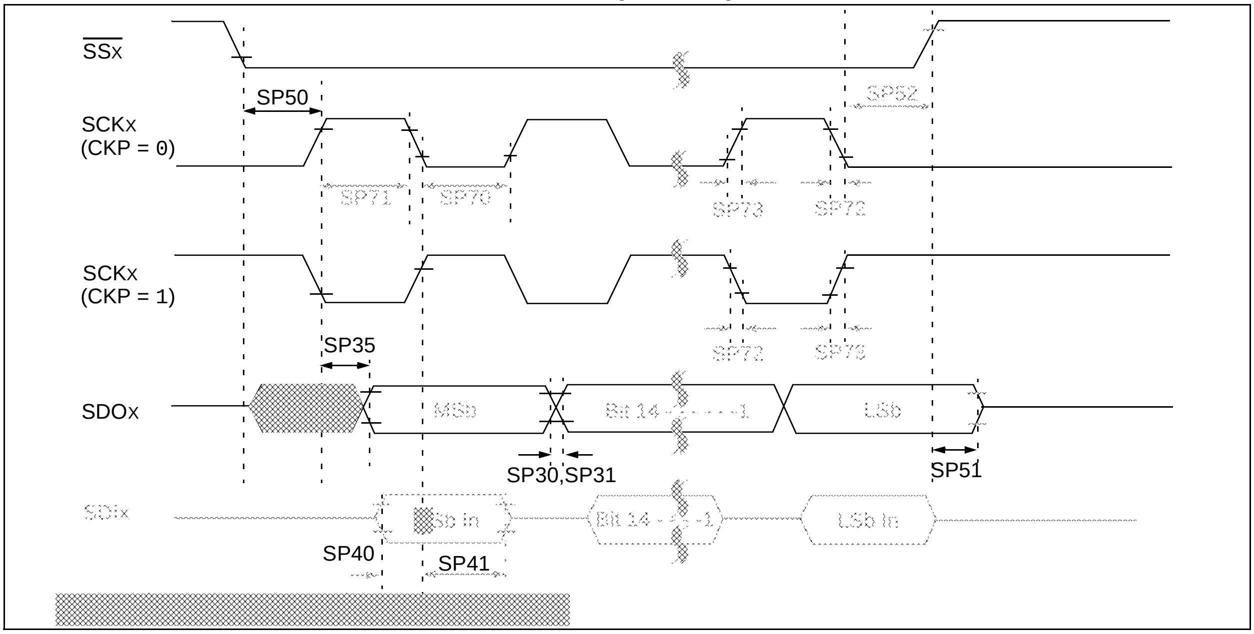


TABLE 32-30: SPIx MODULE SLAVE MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics[1]**	**Min.**	**Typ.[2]**	**Max.**	**Units**	**Conditions**
SP70	TscL	SCKx Input Low Time[3]	Tsck/2	—	—	ns	—
SP71	TscH	SCKx Input High Time[3]	Tsck/2	—	—	ns	—
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See parameter DO32
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See parameter DO31
SP30	TdoF	SDOx Data Output Fall Time[4]	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time[4]	—	—	—	ns	See parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	15	ns	VDD > 2.7V
			—	—	20	ns	VDD < 2.7V
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↑ or SCKx Input	175	—	—	ns	—
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance[3]	5	—	25	ns	—
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ after SCKx Edge	Tsck + 20	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.
2: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.
3: The minimum clock period for SCKx is 40 ns.
4: Assumes 50 pF load on all SPIx pins.

FIGURE 32-27: PARALLEL MASTER PORT WRITE TIMING DIAGRAM

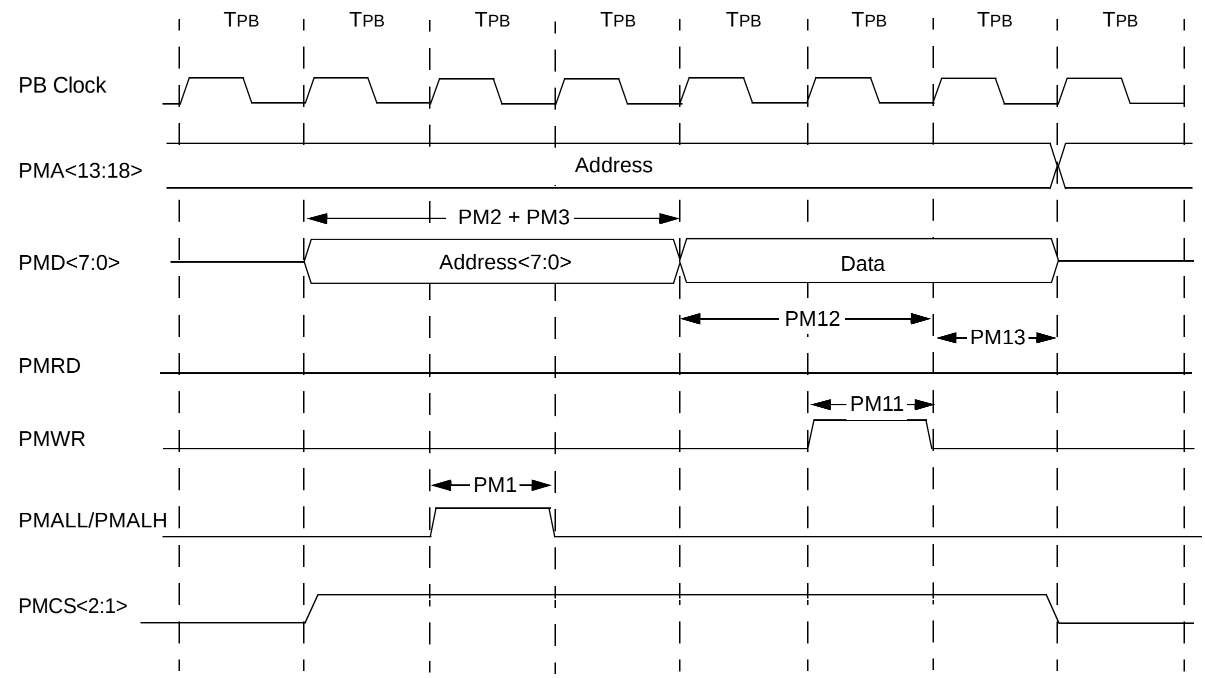


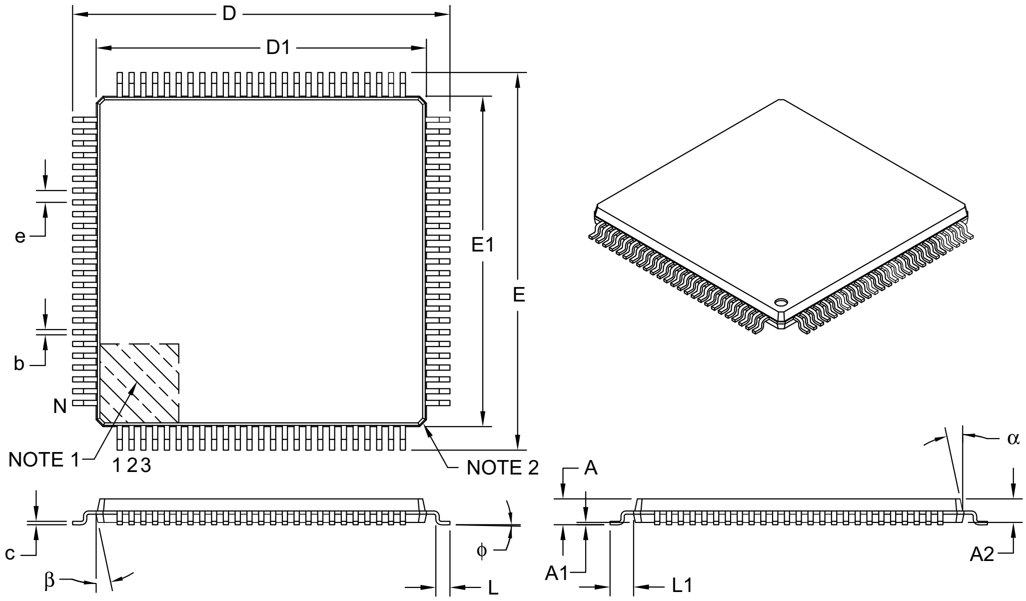
TABLE 32-41: PARALLEL MASTER PORT WRITE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
PM11	TWR	PMWR Pulse Width	—	1 TPB	—	—	—
PM12	TDVSU	Data Out Valid before PMWR or PMENB goes Inactive (data setup time)	—	2 TPB	—	—	—
PM13	TDVHOLD	PMWR or PMEMB Invalid to Data Out Invalid (data hold time)	—	1 TPB	—	—	—

Note 1: These parameters are characterized, but not tested in manufacturing.

100-Lead Plastic Thin Quad Flatpack (PF) – 14x14x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		100	
Lead Pitch	e		0.50 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	φ	0°	3.5°	7°
Overall Width	E		16.00 BSC	
Overall Length	D		16.00 BSC	
Molded Package Width	E1		14.00 BSC	
Molded Package Length	D1		14.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

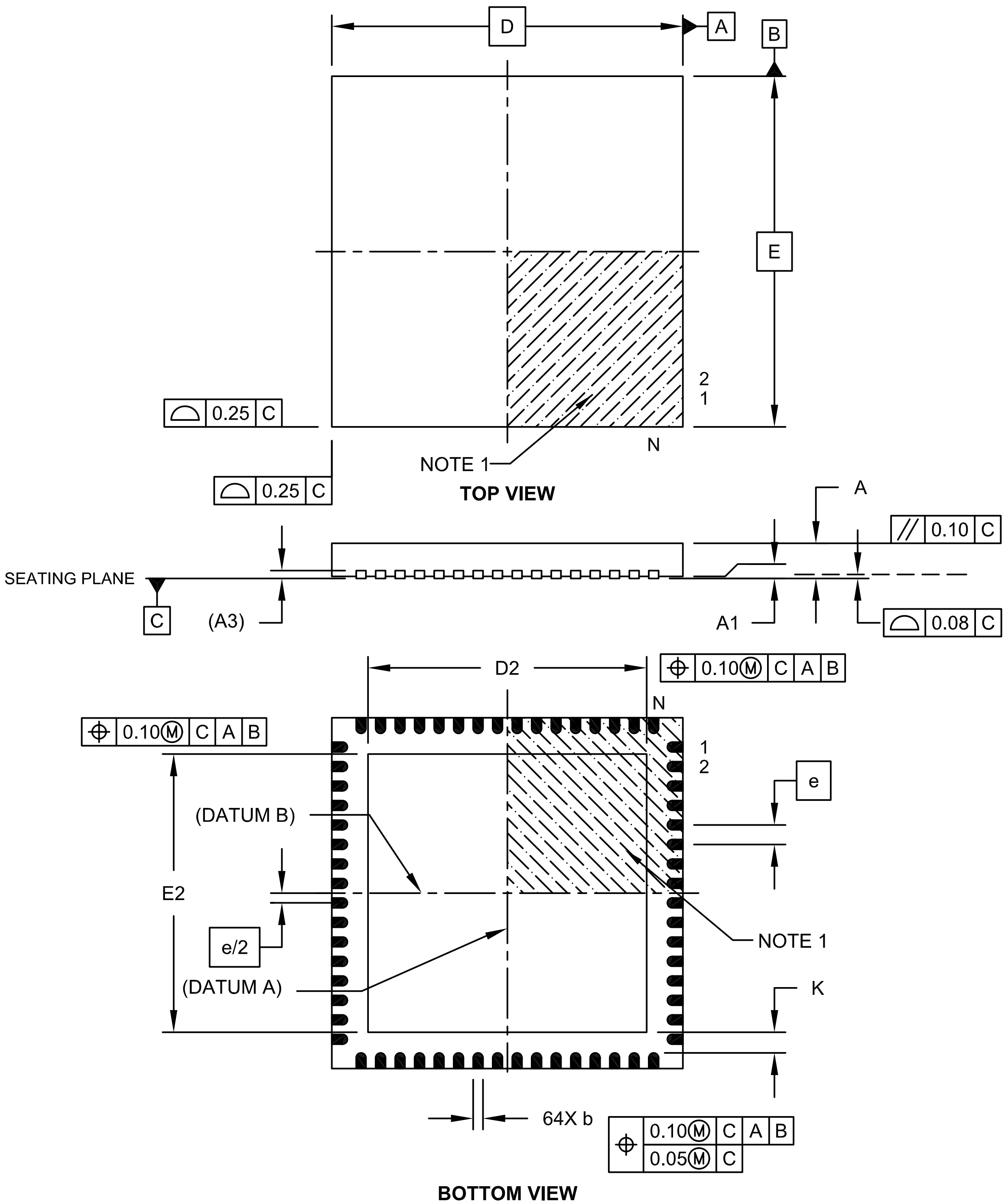
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-110B

64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [QFN] With 7.15 x 7.15 Exposed Pad [QFN]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-149C Sheet 1 of 2